



State of 3D Vacuum Arc Discharge Simulation via PIC-DSMC

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¹Nanoscale and Reactive Processes,

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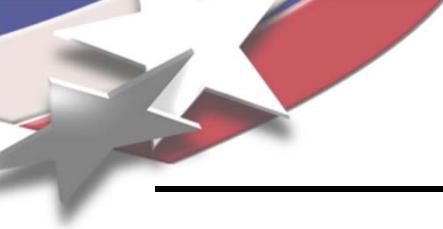
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Outline

1. Our needs
2. Modeling tool, Aleph
3. Complex models need CV & V & SV & SA & UQ
4. Current 3D vacuum arc modeling



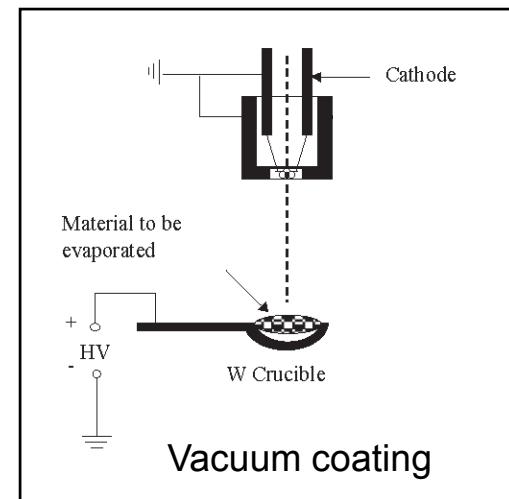
SNL Modeling Needs

We're interested in low temperature collisional plasma phenomena. Our applications generally share the following requirements:

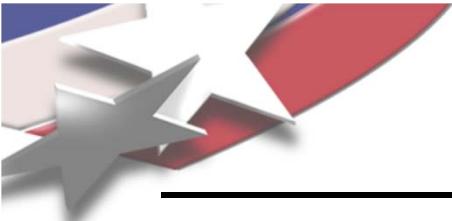
- Kinetic description.
- Collisions/chemistry, including ionization (arcs). Neutrals are important.
- Very large variations in number densities over time and space.
- Sheaths.
- Real applications with complex geometry.

Examples:

- Vacuum arc discharge
- Plasma processing
- Spark gap devices
- Gas switches
- Ion and neutral beams

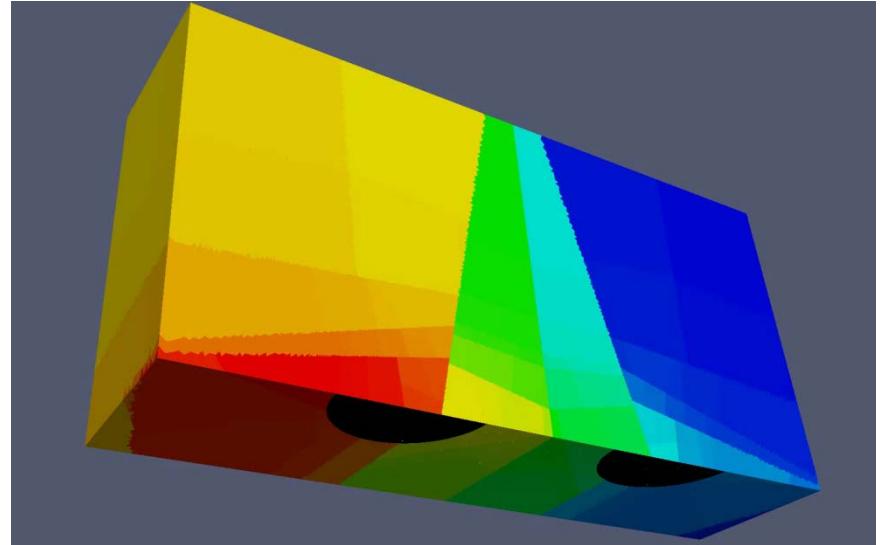


We are especially interested in the transient start-up of arc-based devices.



Description of Aleph

- 1, 2, or 3D Cartesian
- Unstructured FEM (compatible with CAD)
- Massively parallel
- Hybrid PIC + DSMC (PIC-MCC)
- Electrostatics
- Fixed B field
- Solid conduction
- e- approximations (quasi-neutral ambipolar, Boltzmann)
- Dual mesh (Particle and Electrostatics/Output)
- Advanced surface (electrode) physics models
- Collisions, charge exchange, chemistry, excited states, ionization
- Advanced particle weighting methods
- Dynamic load balancing (tricky)
- Restart (with all particles)
- Agile software infrastructure for easily extending BCs, post-processed quantities, etc.
- Currently utilizing up to 32K processors (>100M elements, >1B particles)



256 core particle load balancing example



CV & SV & V & SA & UQ

All Interesting Arc/Plasma Behavior Is Nonlinear And Coupled – How Can We Be Confident In Our Predictions?

CV: Code Verification. Necessary, woefully insufficient. Can test single simple capabilities

SV: Solves right

V: Validates reality solutions

SA: Sensitivity Determination

prediction, experimental result, and/or validation comparison.

Identifies problem areas and is a source of planning decisions/efficiency.

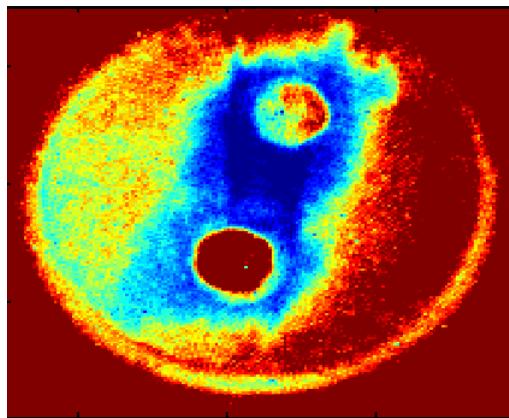
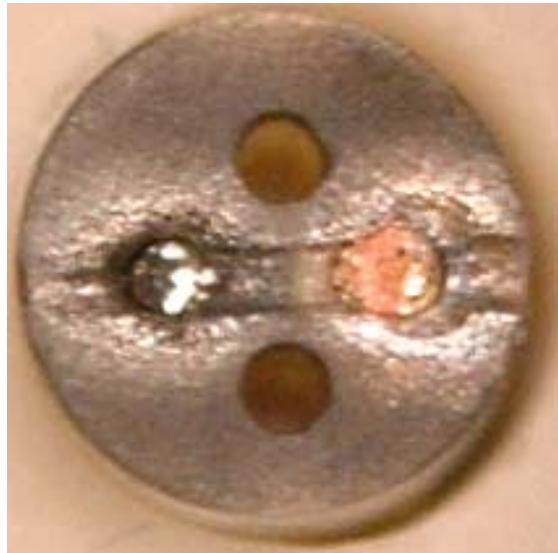
UQ: Uncertainty Quantification. Estimate uncertainty in a code prediction, usually without experimental comparator. Incorporates error estimation and quantified code prediction uncertainties.

**ALL OF THIS IS MORE COMPLICATED
BECAUSE OUR BASIC MODELING METHODS
ARE STOCHASTIC (PIC, MCC, MD, ...) AND
DO NOT HAVE TYPICAL “GRID
CONVERGENCE” BEHAVIOR**

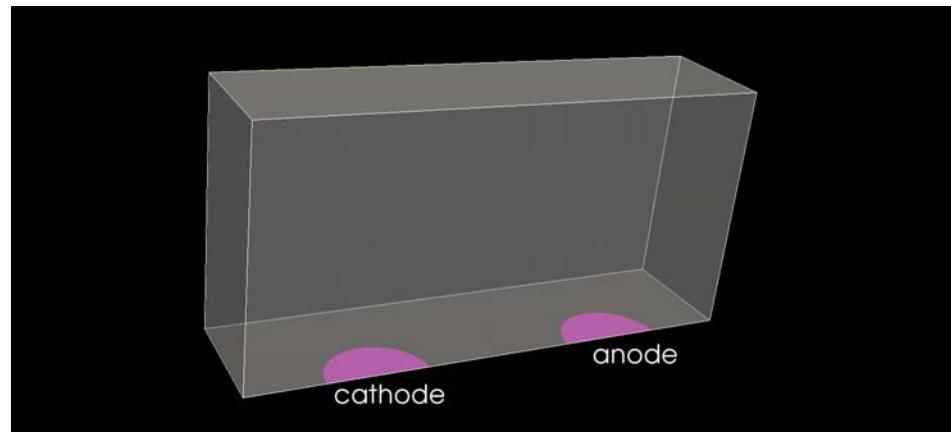
Paul's poster



3D Model of Cu-Cu Arc System

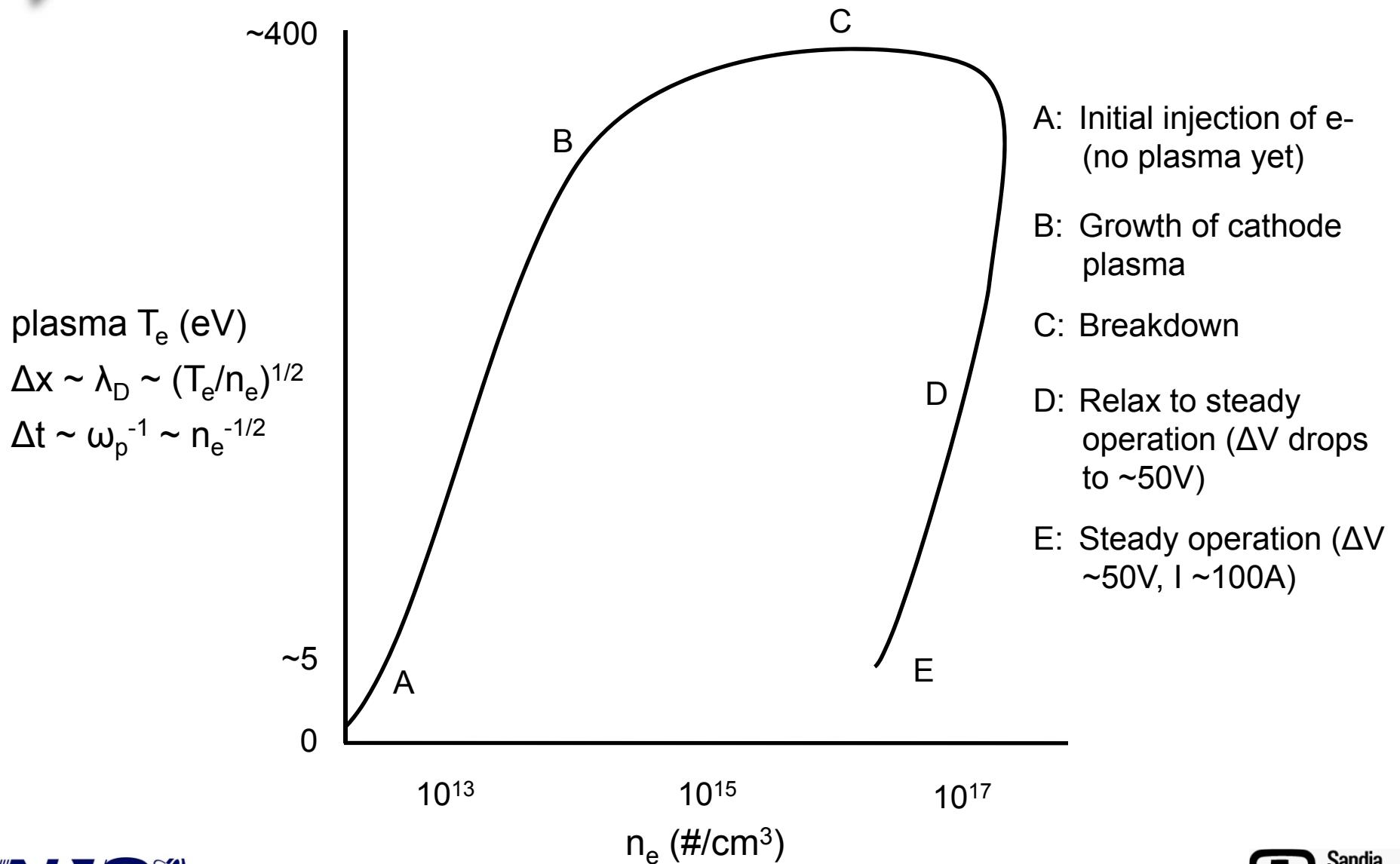


At vacuum
1.5 mm inner-to-inner distance
0.75 mm diameter electrodes
Copper electrodes (this picture is Cu-Ti)
2 kV drop across electrodes
20Ω resistor in series
Steady conditions around 50V, 100A
Breakdown time \ll 100ns
Ionization mfp = 1.5 mm at maximum σ
 $\rightarrow n_i \sim 10^{16} - 10^{17} \text{ #/cm}^3$





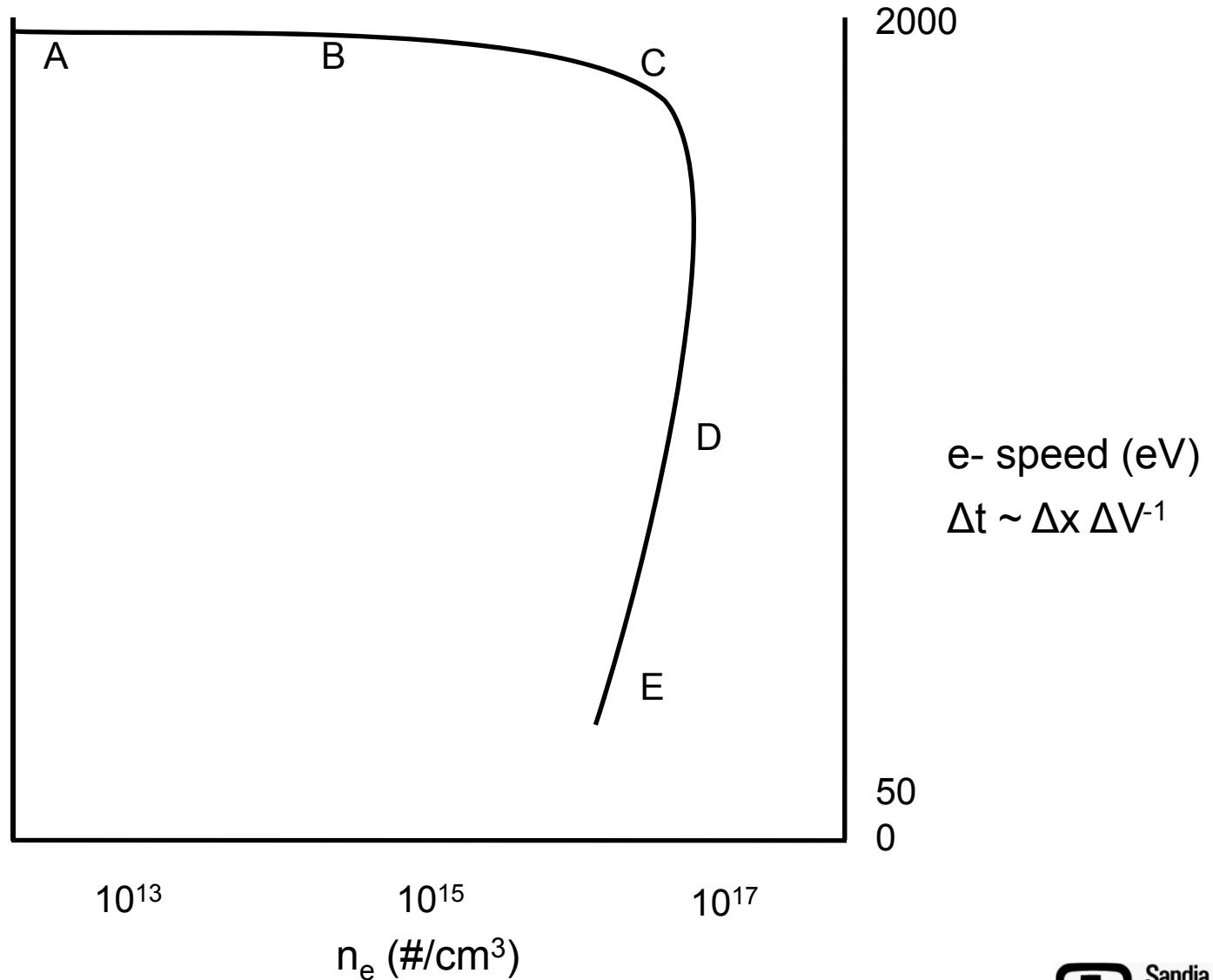
3D Model of Cu-Cu Arc System





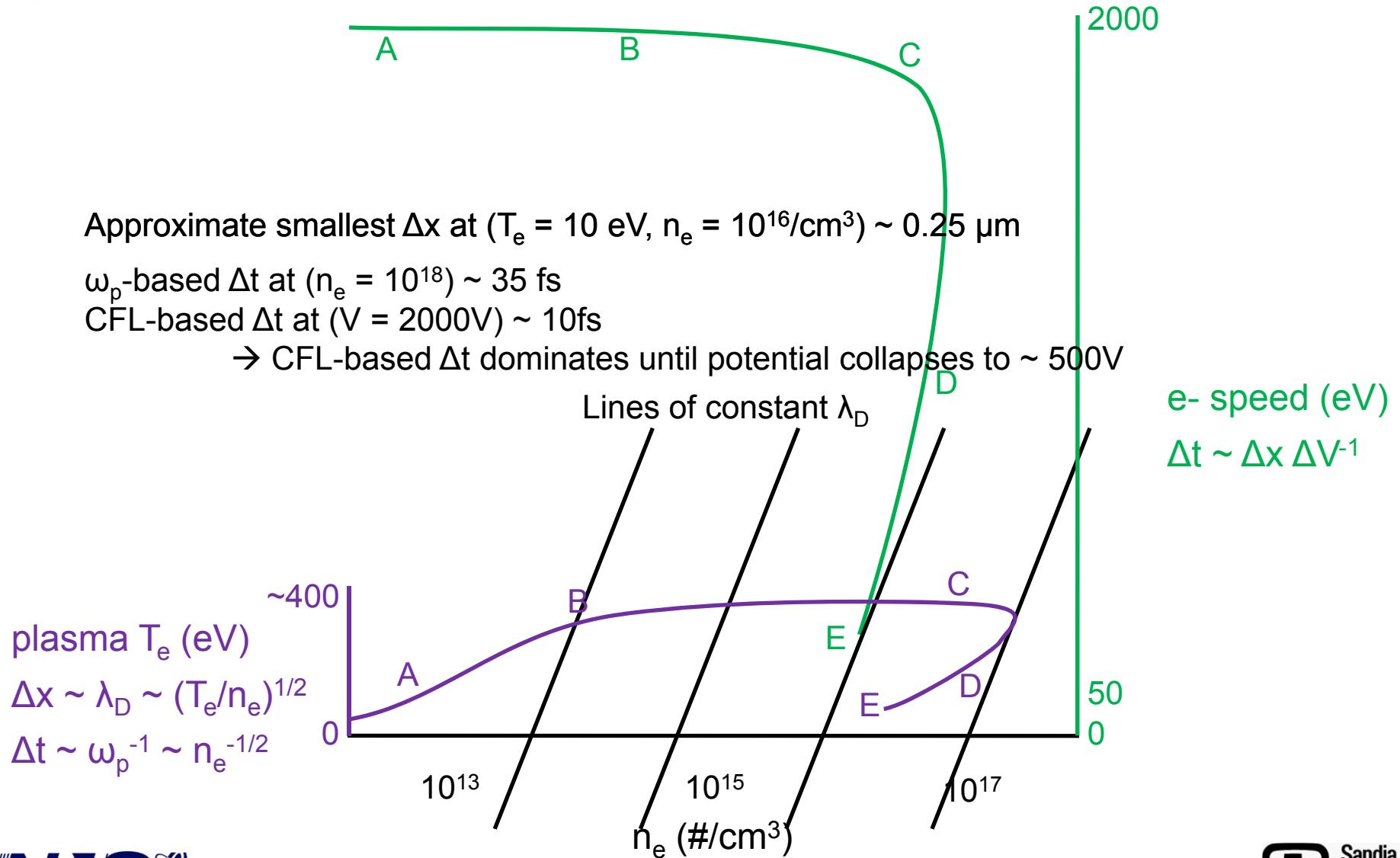
3D Model of Cu-Cu Arc System

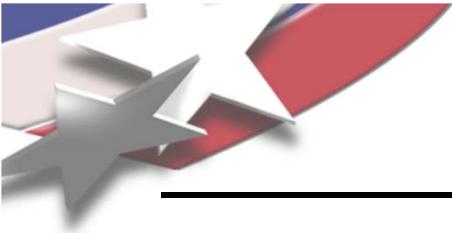
- A: Initial injection of e- (no plasma yet)
- B: Growth of cathode plasma
- C: Breakdown
- D: Relax to steady operation (ΔV drops to $\sim 50V$)
- E: Steady operation ($\Delta V \sim 50V$, $I \sim 100A$)





3D Model of Cu-Cu Arc System





3D Model of Cu-Cu Arc System

$$4 \text{ mm} \times 1.5 \text{ mm} \times 2 \text{ mm} = 24 \text{ mm}^3$$

- + $\text{vol}_E = 0.1 \mu\text{m}^3$
- + ~ 5% of volume is at smallest Δx

~ 5B elements

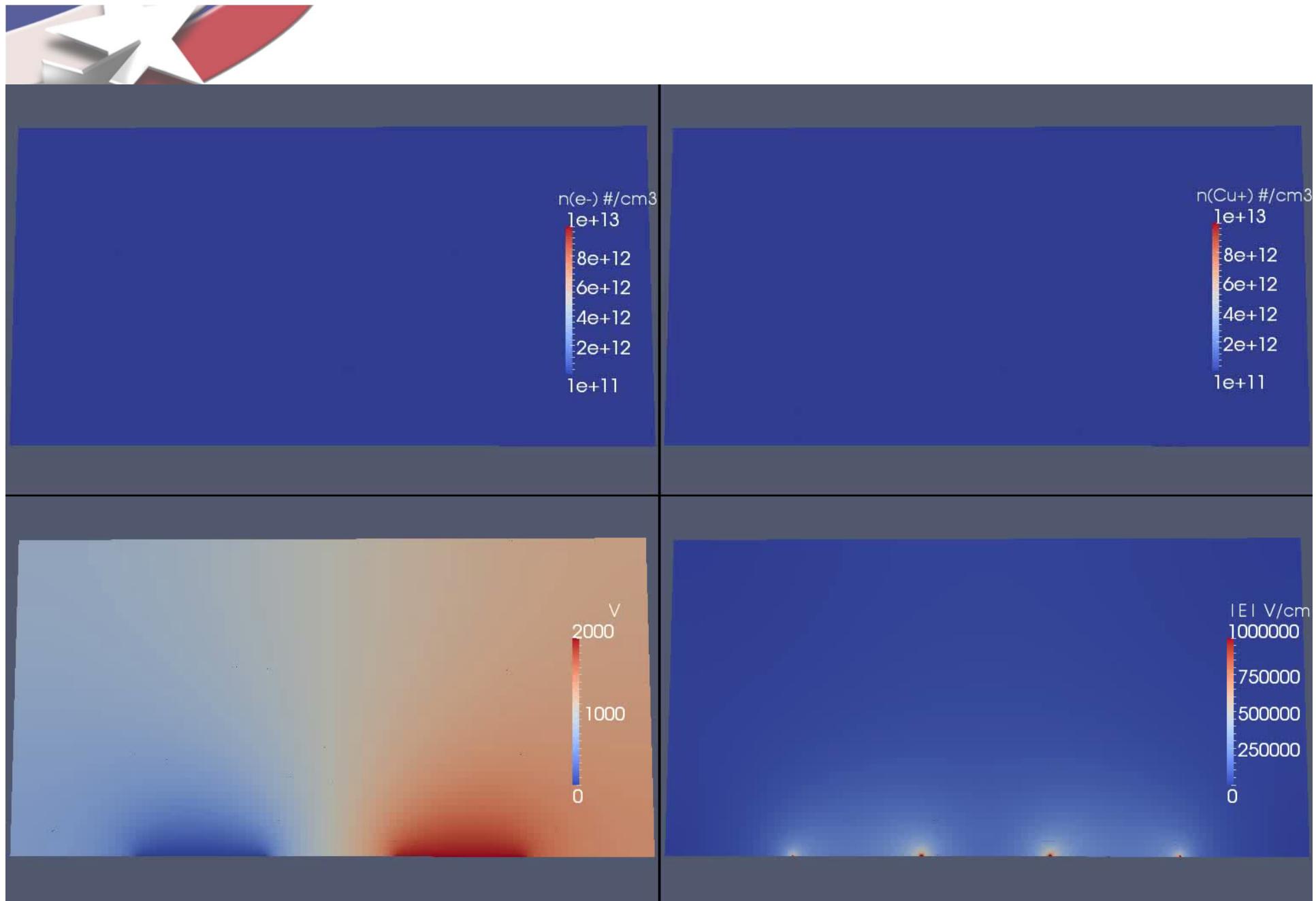
~ 10 ns breakdown time at $\Delta t = 10 \text{ fs}$

- + ~ 100 ns evolution time at $\Delta t = 100 \text{ fs}$
- + ~ 5% of volume is at smallest Δx

2M timesteps

... assuming fixed work per timestep, which is why we developed dynamic particle weighting (keep # particles/element fixed)

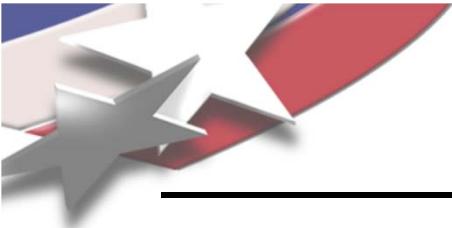
... not there, yet. Results are 1/10th domain size, 2x Δx , 10^{18} background Cu ... on 256 cores ... awaiting better meshing capability ...







The End



Description of Aleph

Basic algorithm for one time step of length Δt :

1. Given known electrostatic field \mathbf{E}^n , move each particle for $\frac{\Delta t}{2}$ via:

$$v_i^{n+1/2} = v_i^n + \frac{\Delta t}{2} \left(\frac{q_i}{m_i} \mathbf{E}^n \right)$$

$$x_i^{n+1} = x_i^n + \Delta t v_i^{n+1/2}$$

2. Compute intersections (non-trivial in parallel).
3. Transfer charges from particle mesh to static mesh.
4. Solve for \mathbf{E}^{n+1} ,

$$\nabla \cdot (\epsilon \nabla V^{n+1}) = -\rho(\mathbf{x}^{n-1})$$

$$\mathbf{E}^{n+1} = -\nabla V^{n+1}$$

5. Transfer fields from static mesh to dynamic mesh.
6. Update each particle for another $\frac{\Delta t}{2}$ via:

$$v_i^{n+1} = v_i^{n+1/2} + \frac{\Delta t}{2} \left(\frac{q_i}{m_i} \mathbf{E}^{n-1} \right)$$

7. Perform DSMC collisions: sample pairs in element, determine cross section and probability of collision. Roll a digital die, and if they collide, re-distribute energy.
8. Perform chemistry: for each reaction, determine expected number of reactions. Sample particles of those types, perform reaction (particle creation/deletion).
9. Reweight particles.
10. Compute post-processing and other quantities and write output.
11. Rebalance particle mesh if appropriate (variety of determination methods).

